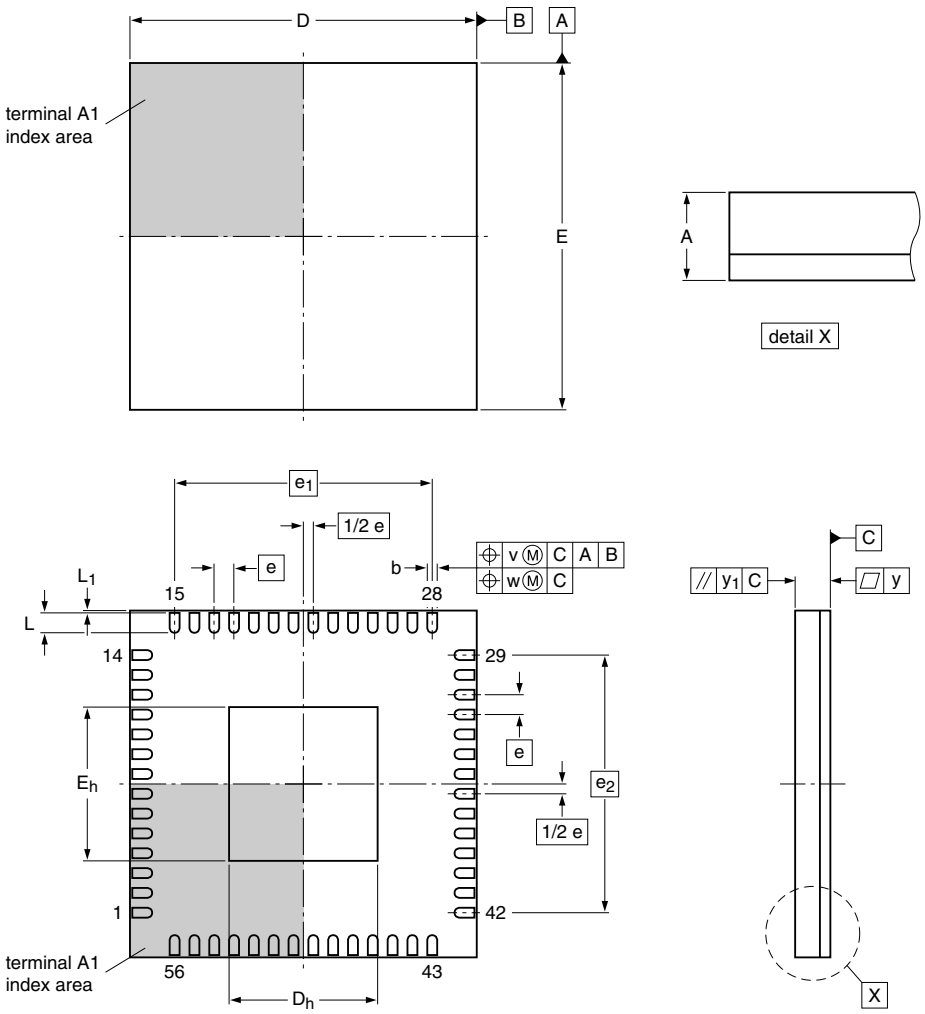
Package outline

HWQFN56R: plastic thermal enhanced very very thin quad flat package; no leads; 56 terminals; resin based; body 7 x 7 x 0.7 mm **SOT1114-1**



Dimensions

Unit		A	b	D	D_h	E	E_h	e	e_1	e_2	L	L_1	v	w	y	y_1
	max	0.80	0.23	7.1	3.1	7.1	3.3				0.43	0.10				
mm	nom	0.70	0.20	7.0	3.0	7.0	3.2	0.4	5.2	5.2	0.40	0.05	0.1	0.05	0.05	0.1
	min	0.65	0.17	6.9	2.9	6.9	3.1				0.37	0.00				

sot1114-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1114-1	- - -	- - -	- - -			~~08-09-16~~ 08-10-07

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